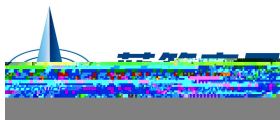


/ Revised record

版本	修订日期	有修订的页码	修订涉及的内容	拟制	审核
A	2022-4-19		首次制定 	黄超	庞隆基



/ Descriptions

SOT-23 PNP Silicon PNP Digital transistor in a SOT-23 Plastic Package.

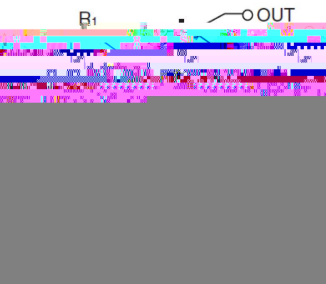
/ Features

With built-in bias resistors, simplify circuit design, reduce a quantity of parts and manufacturing process,HF Product.

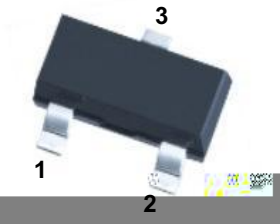
/ Applications

Switching applications, interface circuit and driver circuit applications.

/ Equivalent Circuit



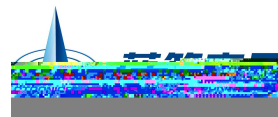
/ Pinning



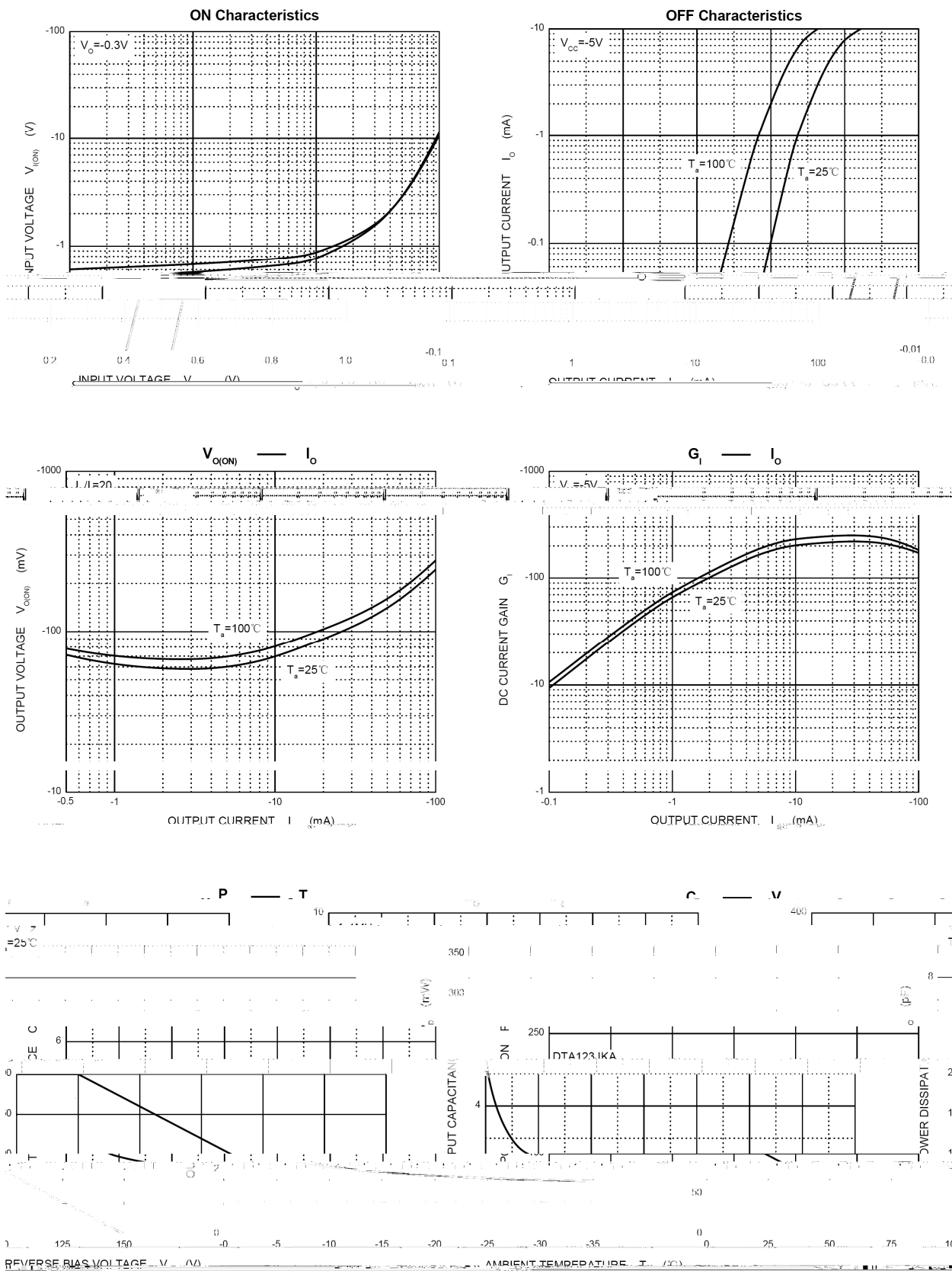
PIN 1 IN PIN 2 GND PIN 3 OUT

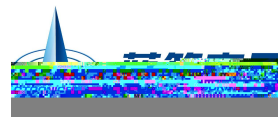
/ Marking

Marking	HE32
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/ Electrical Characteristic Curve

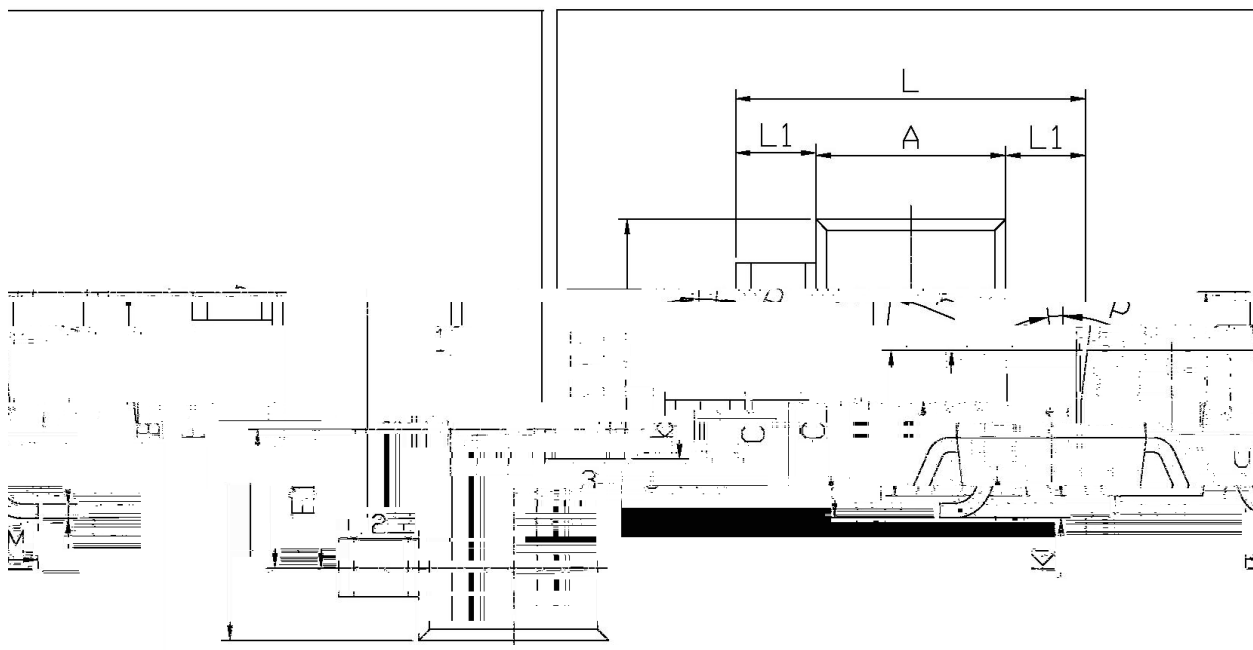




/ Package Dimensions

單位: mm

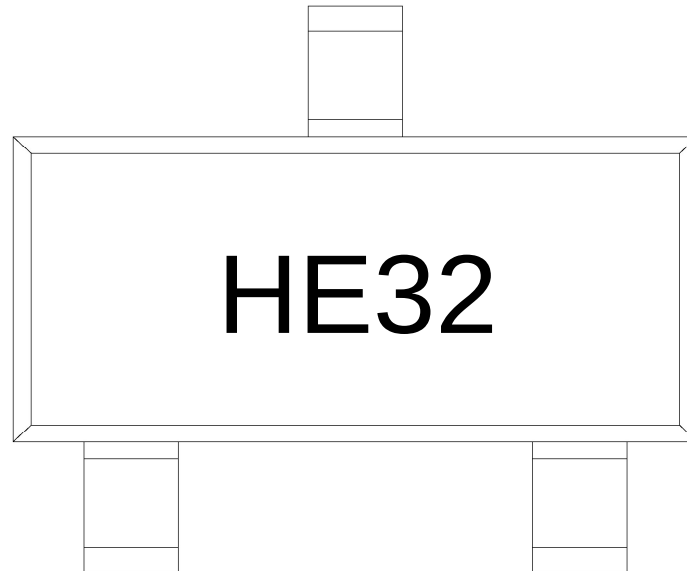
單位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters		
	Min	Max		Min	Max	
L	2.2	2.7	C	1.30Max		
1.20			0.45	0.65	C1	0.90
0.20			0.15	0.50	C2	0.05
0.10			0.70	3.10	K	0
0.35	0.05	0.55	7°			
0.35	0.55					



/ Marking Instructions



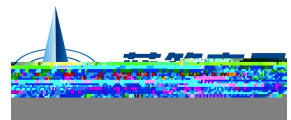
H

E32

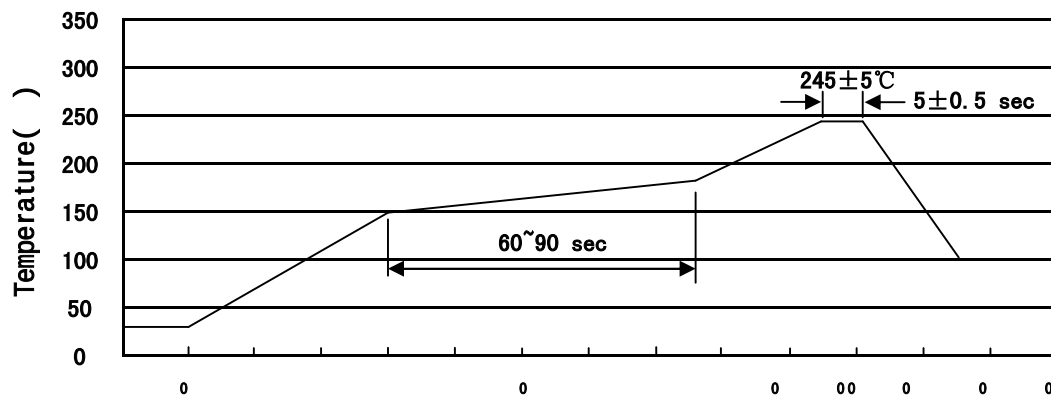
Note:

H Company Code

E32 Product Type



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|--|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | | 2 | 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205

/ Notices